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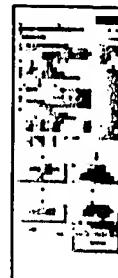
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>Title: JP02111883A2: ELECTROLESS METAL PLATING METHOD

Derwent Title: Electroless metal plating for high density coating - involves adsorbing reducing agent on substrate, dipping in soln. contg. catalytic metal ions, etc. [\[Derwent Record\]](#)

Country: JP Japan

Kind: A



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Priority Number: 1988-10-20 JP1988000265711

Abstract: PURPOSE: To form a uniform dense metal plating film having satisfactory adhesion without using a noble metal catalyst by adsorbing a reducing agent on a body to be plated, immersing the body in a soln. contg. ions of a self-catalytic metal, reducing the deposited metal and carrying out electroless plating.

CONSTITUTION: A reducing agent such as an aq. soln. of sodium borohydride is adsorbed on a body to be plated. This body is immersed in an aq. soln. contg. ions of a self-catalytic metal such as Ni, Co or Cu to deposit the metal and the deposited metal is reduced with the reducing agent. The body to be plated is then electroless-plated with a metal such as Ni, Co or Cu. A uniform dense plating film having superior adhesion can be formed without using an expensive noble metal catalyst.

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